

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/08/2022

Details for "THS4032IDGN"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
THS4032IDGN	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DGN   8	3x3x1	27

**\*Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.02865	99.98953	999895	0.106128	1061
Not Categorized	Proprietary Materials		0.000003	0.01047	105	0.000011	0
Sub-Total			0.028653	100	1000000	0.106139	1061
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.215125	81.999863	819999	0.796886	7969
Thermoplastics	Epoxy	85954-11-6	0.047223	18.000137	180001	0.174928	1749
Sub-Total			0.262348	100	1000000	0.971813	9718
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	10.7408	95.9	959000	39.787045	397870
Magnesium and Its Alloys	Magnesium	7439-95-4	0.0196	0.175	1750	0.072604	726
Nickel and Its Alloys	Nickel	7440-02-0	0.3584	3.2	32000	1.327618	13276
Other Inorganic Materials	Silicon	7440-21-3	0.0812	0.725	7250	0.300788	3008
Sub-Total			11.2	100	1000000	41.488055	414881
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.196157	97.299617	972996	0.726623	7266
Precious Metals	Gold	7440-57-5	0.000605	0.300098	3001	0.002241	22
Precious Metals	Palladium	7440-05-3	0.004234	2.100188	21002	0.015684	157
Precious Metals	Silver	7440-22-4	0.000605	0.300098	3001	0.002241	22
Sub-Total			0.201601	100	1000000	0.746789	7468
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	13.028049	93.499995	935000	48.25968	482597
Other Plastics and Rubber	Carbon Black	1333-86-4	0.069669	0.500002	5000	0.258074	2581
Thermoplastics	Epoxy	85954-11-6	0.836025	6.000003	60000	3.09688	30969
Sub-Total			13.933743	100	1000000	51.614634	51646
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.369377	100	1000000	5.07257	50726
Sub-Total			1.369377	100	1000000	5.07257	50726
<b>Total</b>			26.995722			100	1000000

**Important Note**

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, see Product Content Methodology.](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)

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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.